

Simulation on ILC undulator based source with liquid lead target

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ANL

Parameters

- Undulator: $K=0.92$, $l_u=1.15\text{cm}$
- AMD: 6T-0.5T in 14cm, immersed target
- Target: 0.5X0 liquid lead
- Yield estimated at 125MeV using damping ring acceptance window.
- No photon collimator applied
- Distance from target to undulator is 500m



EGS4 and PARMELA results

- Yield is about 2.09 per 100m
- Energy deposition per captured e+ 54.8MeV
- Assuming $2e^{10}$ e+ captured per bunch then energy deposition per bunch is 0.1758 J in target without windows
- Assuming $2e^{10}$ e+ captured per bunch then energy deposition per bunch is 0.18376 J in target, 0.00818J in upstream window (BN) and 0.0436J in downstream window (BN ~ 4 mm).

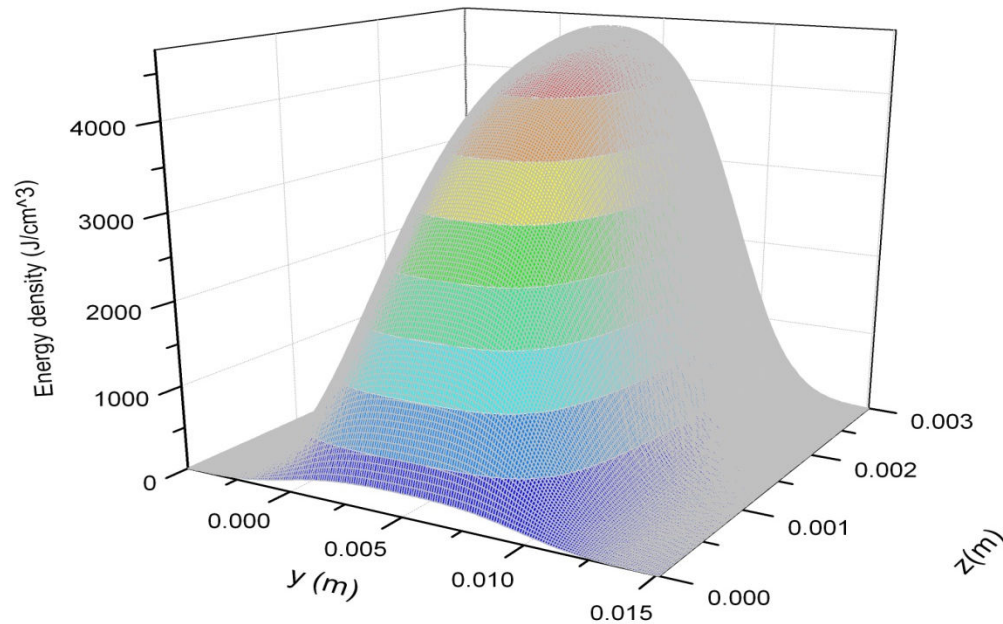


Parameters of liquid lead and BN window

- Energy required to heat the liquid lead from 600K up to boiling point(2022K): $Q_b = \sim 197.7 \text{ J/g} \Leftrightarrow 2241.9 \text{ J/cm}^3$
- Latent heat for vaporization of lead: $Q_L = \sim 871 \text{ J/g} \Leftrightarrow 9877 \text{ J/cm}^3$
- To heat the liquid lead from 600K into vapor needs $Q_v = Q_b + Q_L = \sim 12119 \text{ J/cm}^3$
- Maximum use temperature of BN is $\sim 3000^\circ\text{C}$
- The current window brazing material (?, from Omori,) will be melted at $\sim 900^\circ\text{C}$



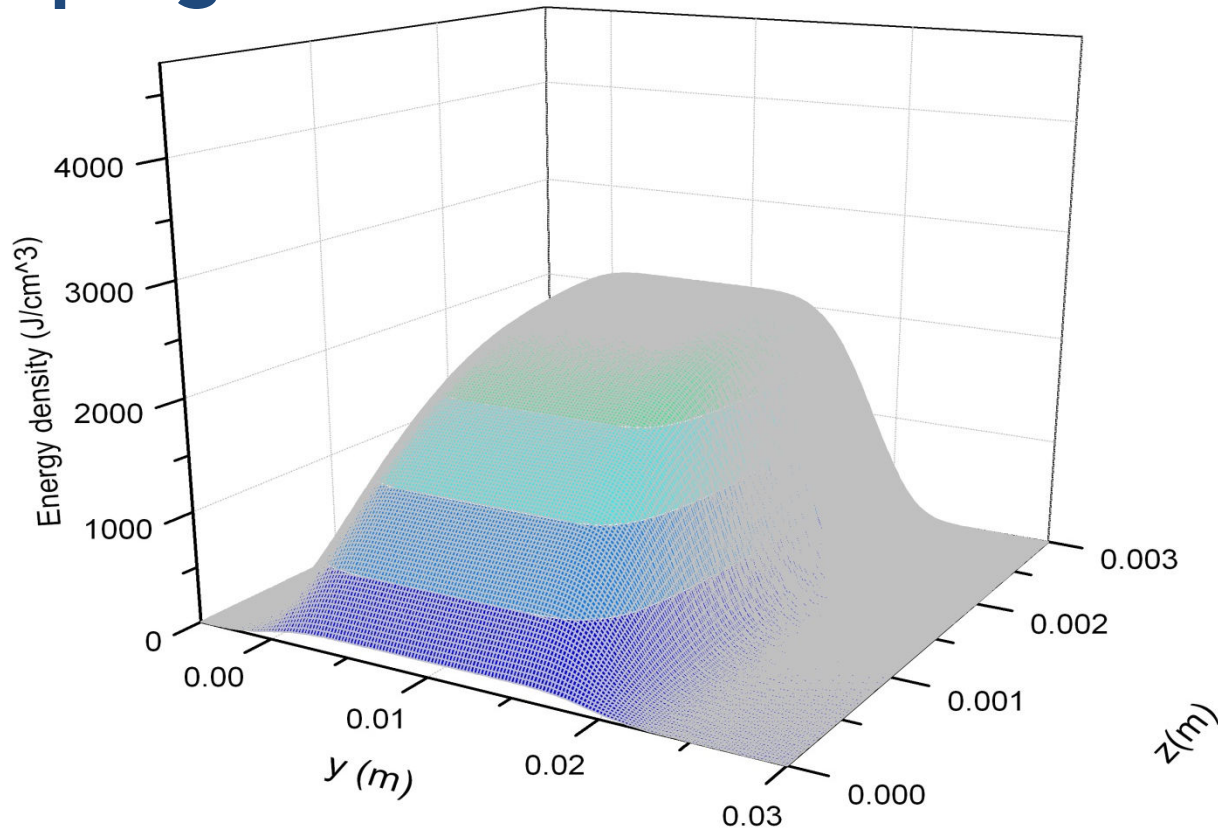
Distribution of deposited energy density pumping at 10m/s



- Energy density goes over 2241J/cm³ easily but stays below the point of vaporization. The lead will stay in liquid form.
- The energy density on window surface is high enough to bring the temperature over the melting point of brazing material for current configuration.



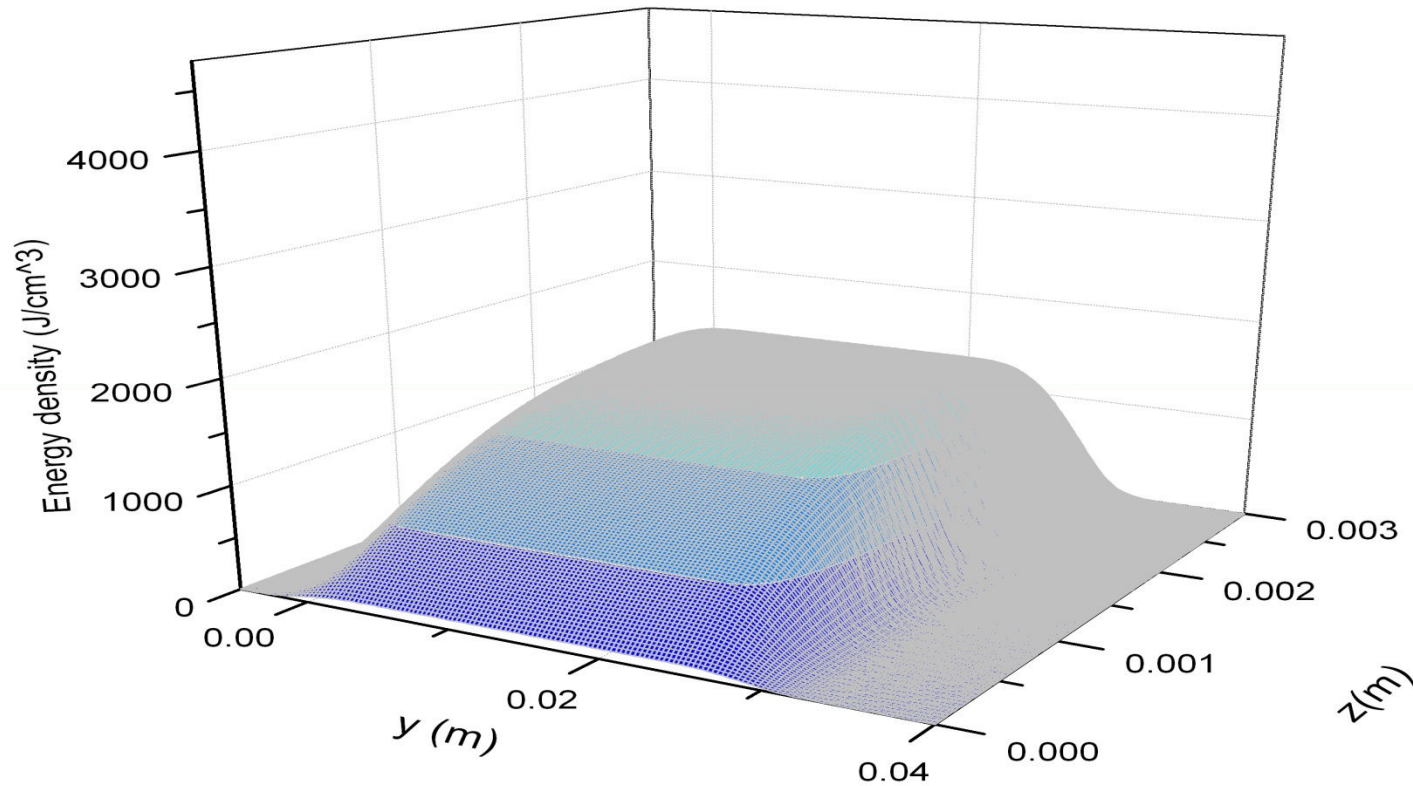
Distribution of deposit energy density pumping at 20m/s



- Energy density goes over 2241J/cm³ by about 200 J/cm³ which is far below the point of vaporization. Lead will stay in liquid form.
- Energy density on window surface stays below the point where temperature will exceed the melting point of brazing material without considering the heat conduction.



Distribution of deposit energy density pumping at 30m/s

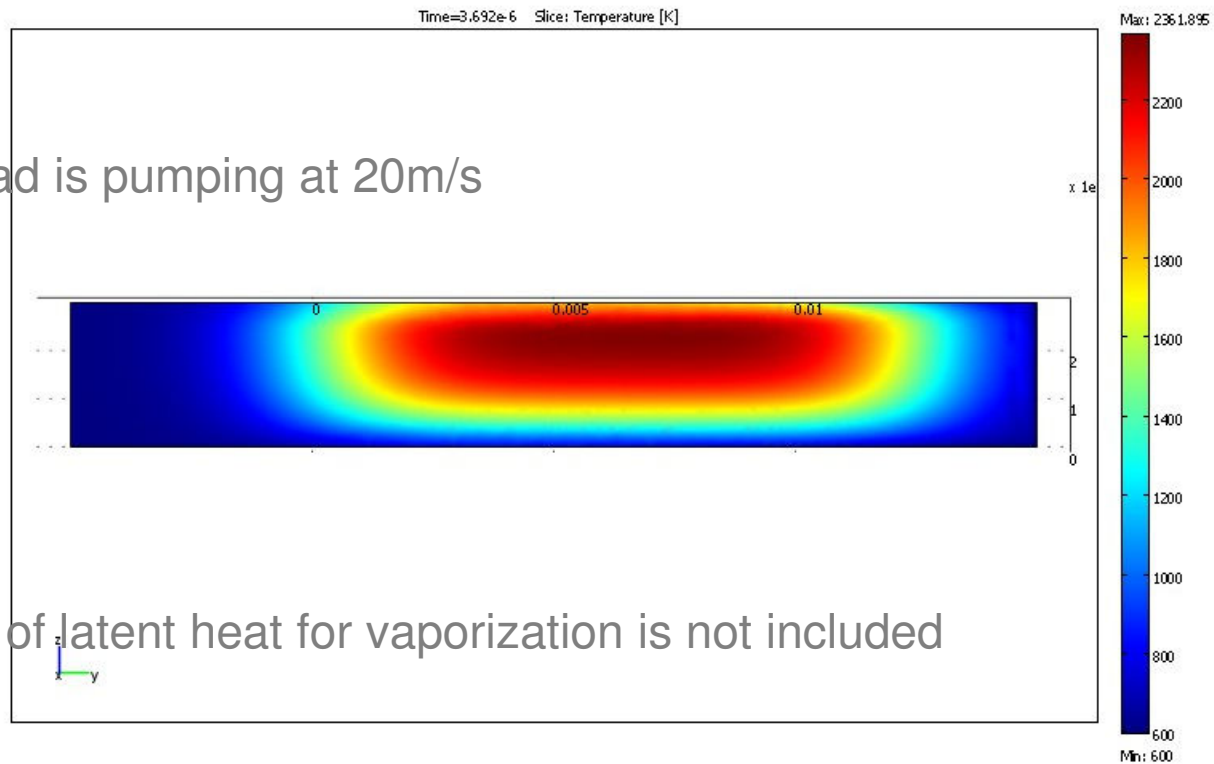


- Energy density stays below 1600J/cm³ in the target and the lead will stay in liquid form.



Heat transfer simulation result without considering the latent heat

The liquid lead is pumping at 20m/s

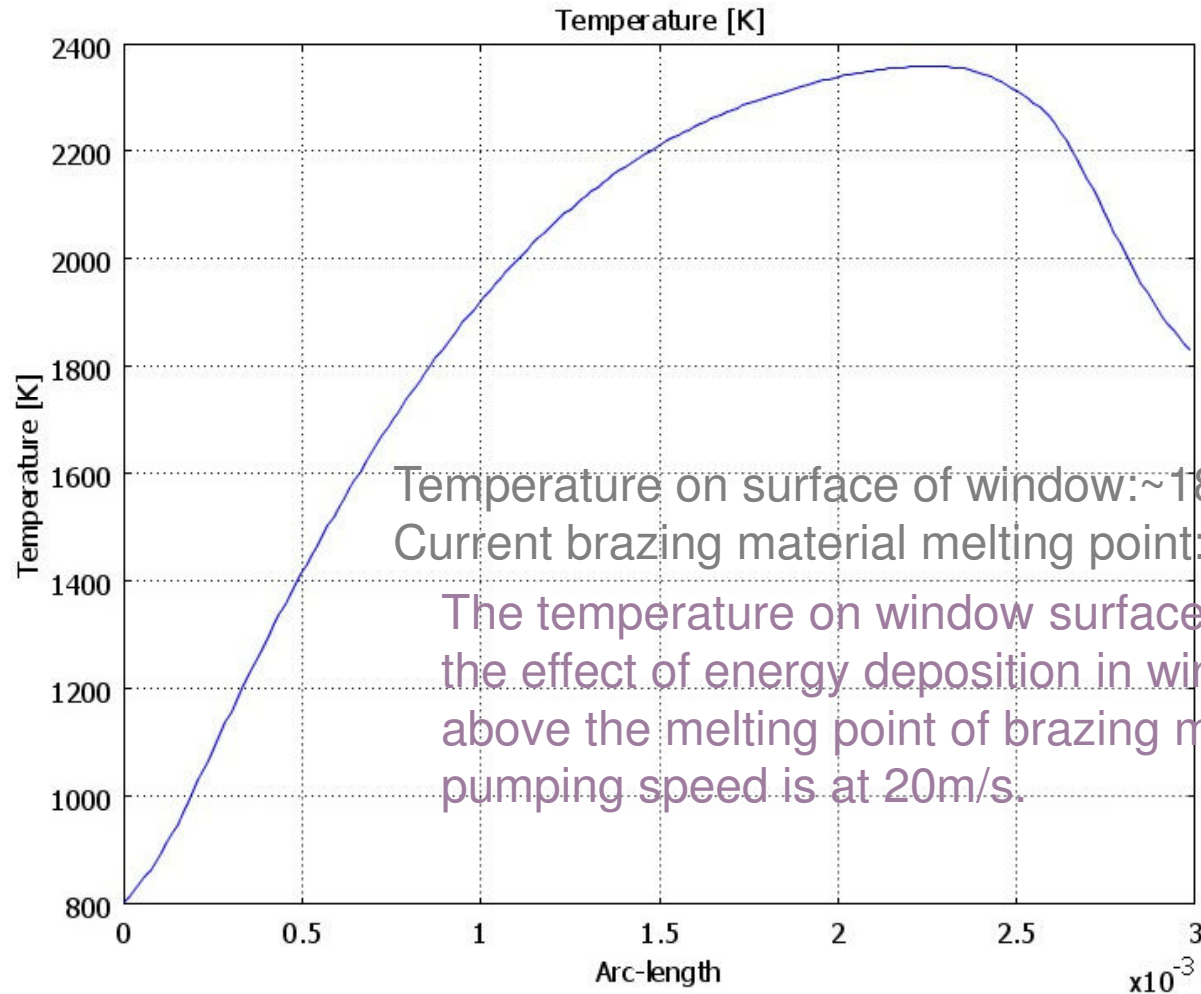


The effect of latent heat for vaporization is not included

With heat conduction considered, the temperature on surface of the window is about 1800K and is higher than the melting point of current window brazing material.



Temperature distribution along the depth of target at the middle of bunch train when pumping speed is 20m/s

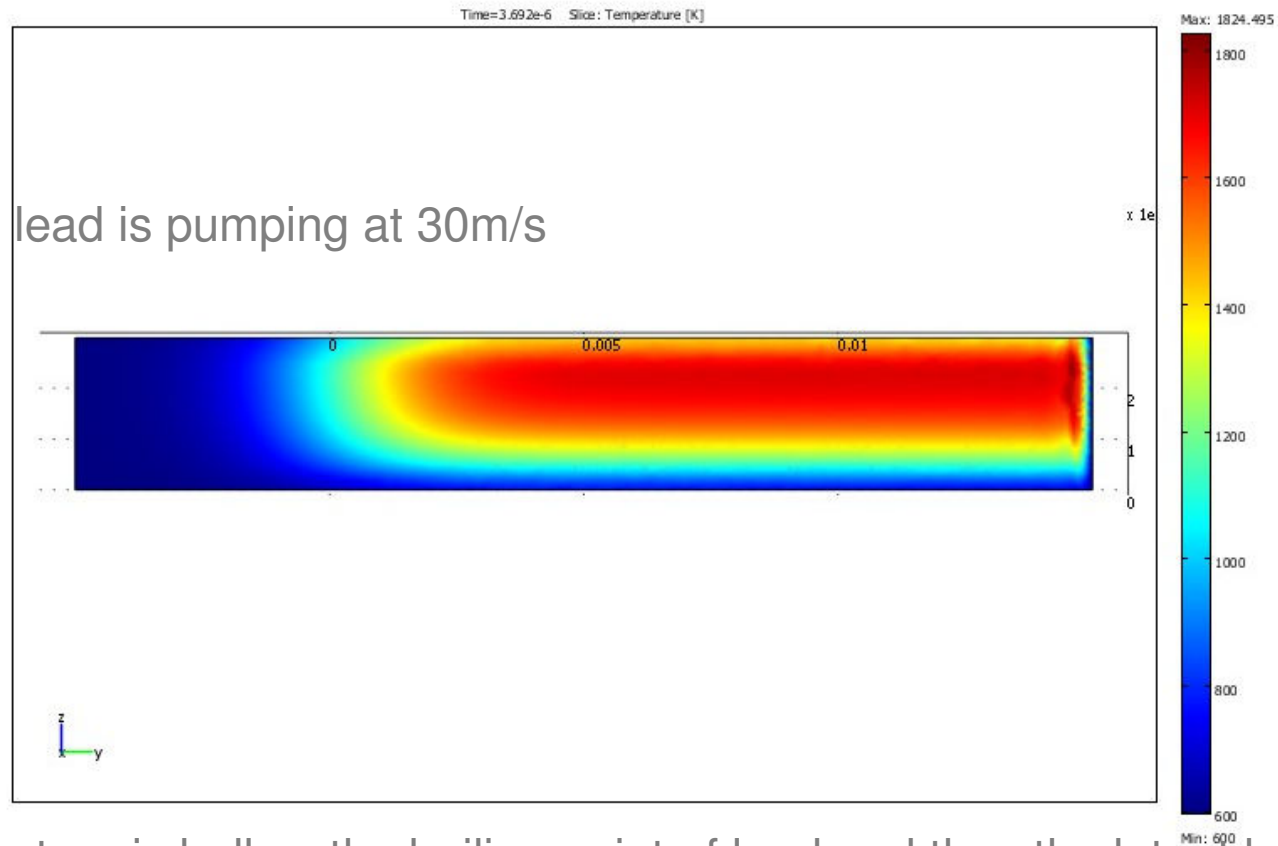


Temperature on surface of window: ~1800K
Current brazing material melting point: ~1200K

The temperature on window surface without considering the effect of energy deposition in window is about 600K above the melting point of brazing material when pumping speed is at 20m/s.

Heat transfer simulation result without considering the latent heat

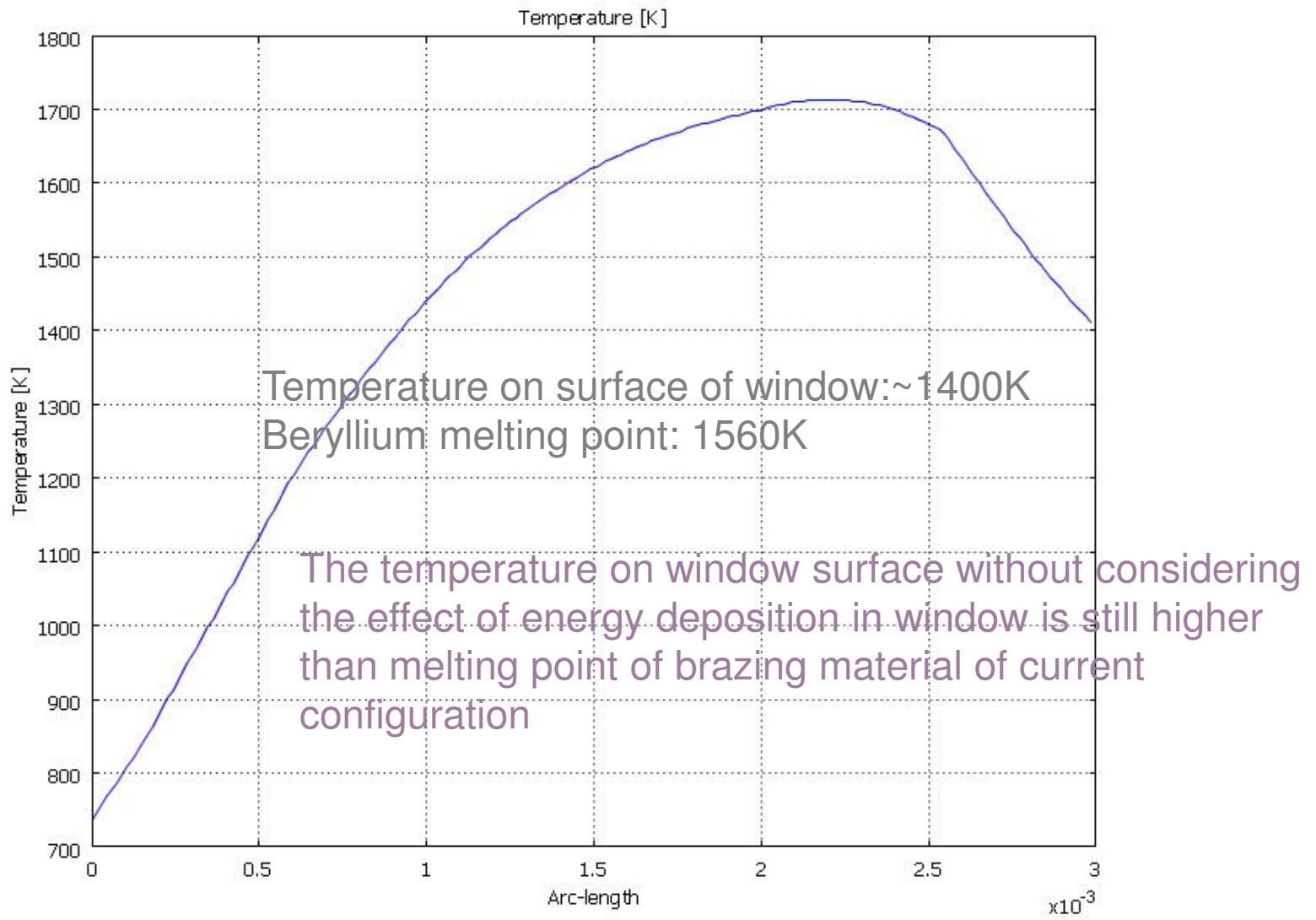
The liquid lead is pumping at 30m/s



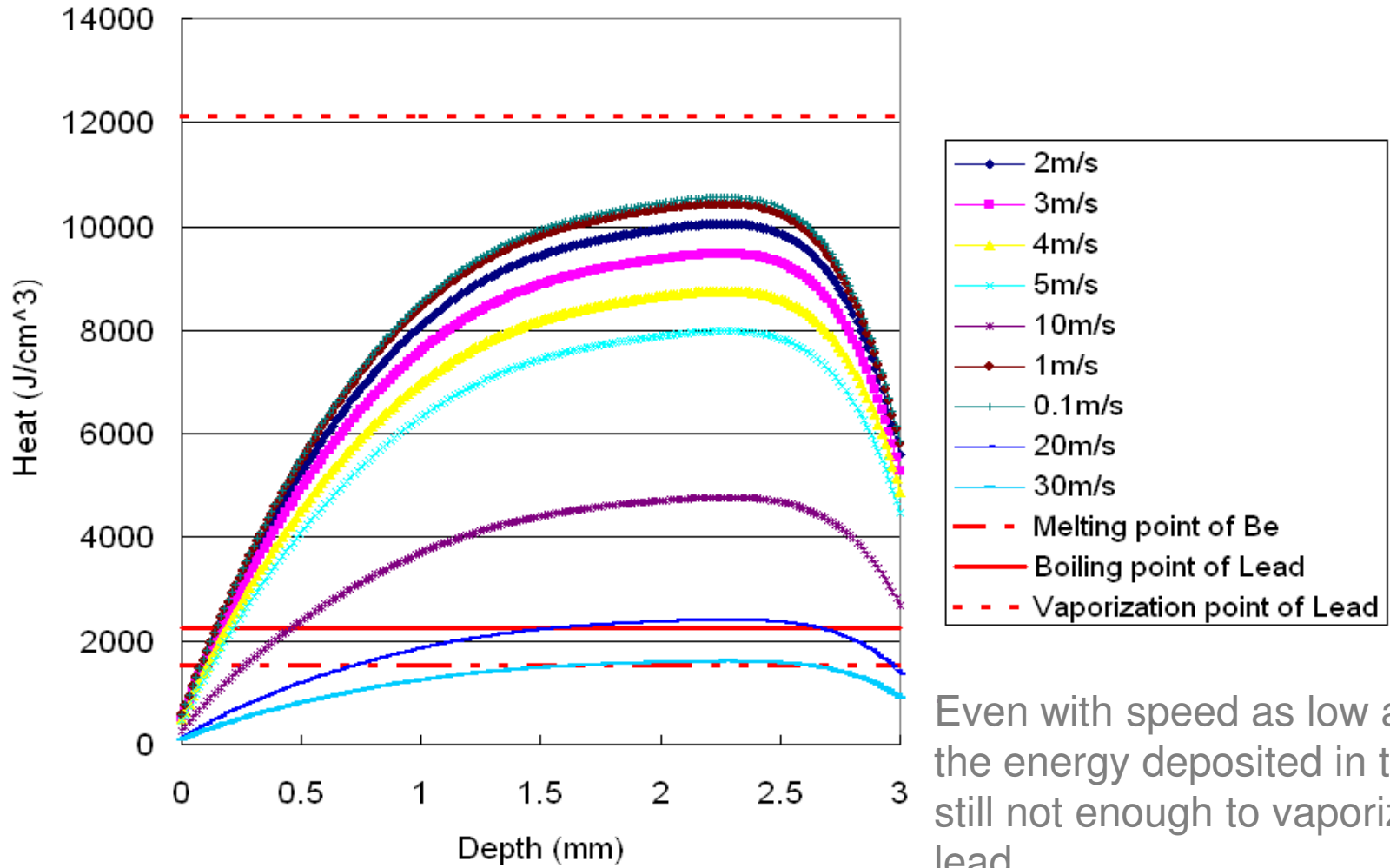
The temperature is below the boiling point of lead and thus the latent has no effect here



Temperature distribution along the depth of target at the middle of bunch train



Heat density at the middle of bunch train for different pumping speeds

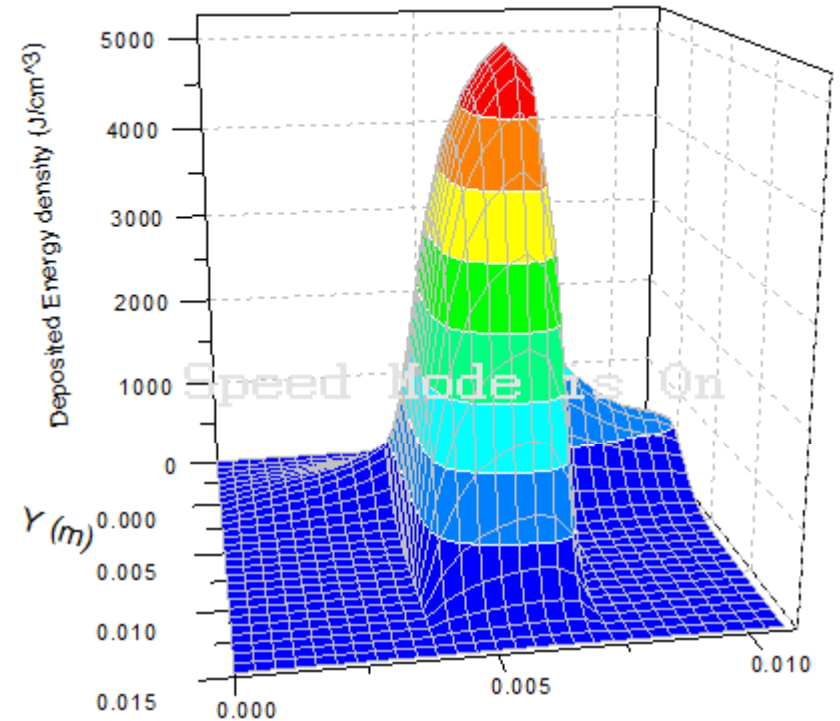
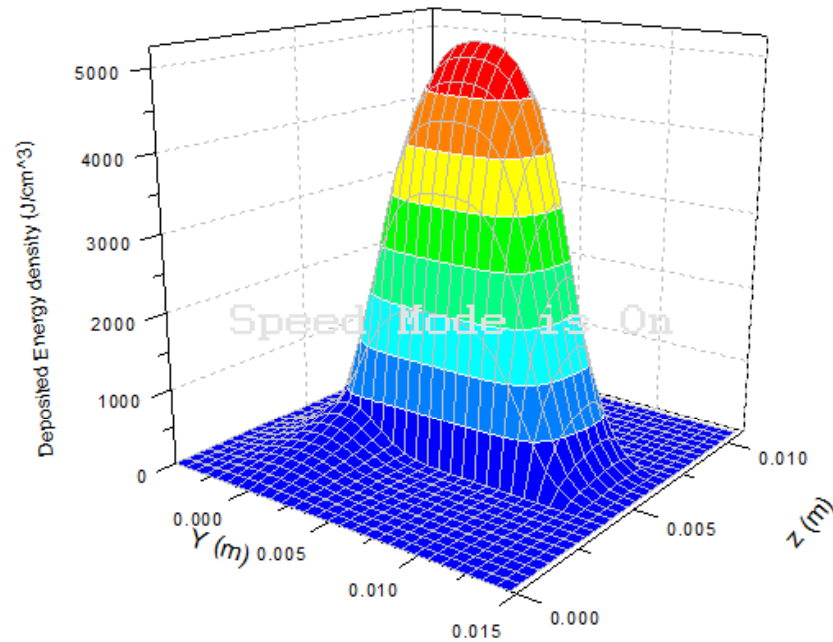


Even with speed as low as 10cm/s the energy deposited in target is still not enough to vaporize the lead.



Energy deposition density in both window and target

Pumping speed is 10m/s



4mm thick BN window applied on both upstream and downstream of liquid lead target. Energy deposition profile for a train of 2625 bunches shows that the energy deposition in window is $< 2000 \text{ J/cm}^3$ which can only increase the temperature of window by $\sim 700\text{K}$ which is far below the maximum working temperature of BN, 3000°C . With 10cm/s pumping, the lead will be at its boiling point 2022K , adding 700K to the downstream window only bring the window up to 2722K . It is still more than about 500K below the maximum using temperature of BN



Summary

- Numerical simulations shows that the undulator based ILC e+ with liquid lead target with BN window will work (if the issue of melting of brazing joint can be overcome).
- The pumping speed can be as low as 10cm/s without vaporizing the liquid lead or melting the BN window.

